



Description

JMT N-channel Enhancement Mode Power MOSFET

Features

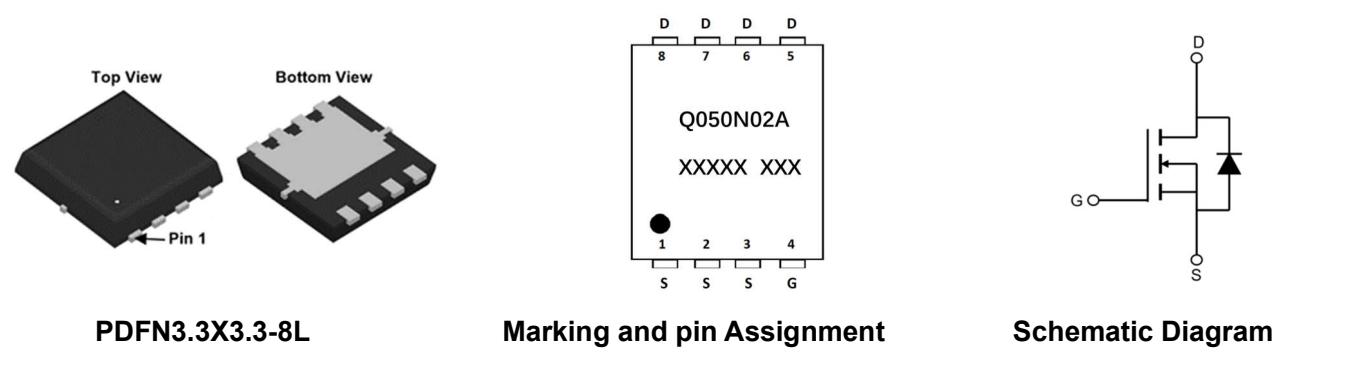
- 20V, 50A
- $R_{DS(ON)} < 5\text{m}\Omega$ @ $V_{GS} = 4.5\text{V}$
- $R_{DS(ON)} < 8\text{m}\Omega$ @ $V_{GS} = 2.5\text{V}$
- Lead free and Green Device Available
- Excellent $R_{DS(ON)}$ and Low Gate Charge
- Lead free product is acquired

Application

- Load Switch
- PWM Application
- Power management



100% UIS TESTED!
100% ΔV_{ds} TESTED!



Package Marking and Ordering Information

Device Marking	Device	OUTLINE	Device Package	Reel Size	Reel (PCS)	Per Carton (PCS)
Q050N02A	JMTQ90N02A	TAPING	PDFN3.3X3.3-8L	13inch	5000	50000

Absolute Maximum Ratings ($T_C=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter		Max.	Units
V_{DSS}	Drain-Source Voltage		20	V
V_{GSS}	Gate-Source Voltage		± 12	V
I_D	Continuous Drain Current	$T_C = 25^\circ\text{C}$	50	A
		$T_C = 100^\circ\text{C}$	33	A
I_{DM}	Pulsed Drain Current ^{note1}		200	A
E_{AS}	Single Pulsed Avalanche Energy ^{note2}		56.2	mJ
P_D	Power Dissipation	$T_C = 25^\circ\text{C}$	21	W
$R_{\theta JC}$	Thermal Resistance, Junction to Case		6	$^\circ\text{C}/\text{W}$
T_J, T_{STG}	Operating and Storage Temperature Range		-55 to +150	$^\circ\text{C}$

**JMTQ050N02A****Electrical Characteristics** ($T_J=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$, $I_D=250\mu\text{A}$	20	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=20\text{V}$, $V_{GS}=0\text{V}$	-	-	1	μA
I_{GSS}	Gate to Body Leakage Current	$V_{GS}=\pm 12\text{V}$, $V_{DS}=0\text{V}$	-	-	± 100	nA
On Characteristics						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_D=250\mu\text{A}$	0.4	0.7	1.0	V
$R_{DS(\text{on})}$ note3	Static Drain-Source On-Resistance	$V_{GS}=4.5\text{V}$, $I_D=30\text{A}$	-	3.8	5	$\text{m}\Omega$
		$V_{GS}=2.5\text{V}$, $I_D=20\text{A}$		5.5	8	
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS}=10\text{V}$, $V_{GS}=0\text{V}$, $f=1.0\text{MHz}$	-	2500	-	pF
C_{oss}	Output Capacitance		-	407	-	pF
C_{rss}	Reverse Transfer Capacitance		-	386	-	pF
Q_g	Total Gate Charge	$V_{DS}=10\text{V}$, $I_D=30\text{A}$, $V_{GS}=4.5\text{V}$	-	23	-	nC
Q_{gs}	Gate-Source Charge		-	3	-	nC
Q_{gd}	Gate-Drain("Miller") Charge		-	7.9	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-On Delay Time	$V_{DS}=10\text{V}$, $I_D=30\text{A}$, $R_G=1.8\Omega$, $V_{GS}=4.5\text{V}$	-	17	-	ns
t_r	Turn-On Rise Time		-	49	-	ns
$t_{d(off)}$	Turn-Off Delay Time		-	74	-	ns
t_f	Turn-Off Fall Time		-	26	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I_s	Maximum Continuous Drain to Source Diode Forward Current		-	-	50	A
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	200	A
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS}=0\text{V}$, $I_{SD}=30\text{A}$, $T_J=25^\circ\text{C}$	-	-	1.2	V

Notes: 1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition: $T_J=25^\circ\text{C}$, $V_{DD}=10\text{V}$, $V_G=4.5\text{V}$, $R_G=25\Omega$, $L=0.5\text{mH}$, $I_{AS}=15\text{A}$ 3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$

Typical Performance Characteristics

Figure 1: Output Characteristics

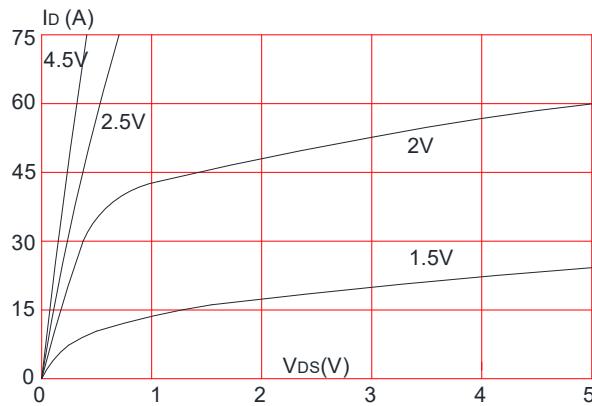


Figure 3: On-resistance vs. Drain Current

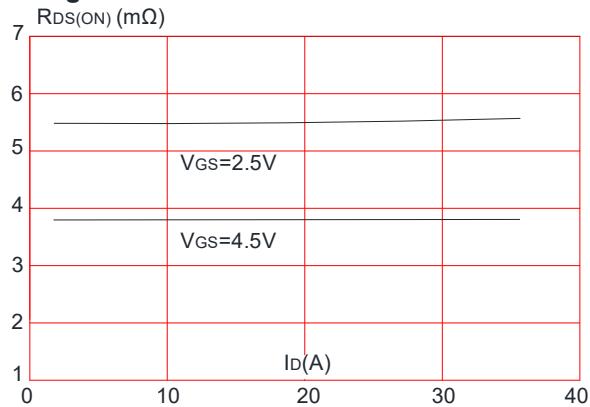


Figure 5: Gate Charge Characteristics

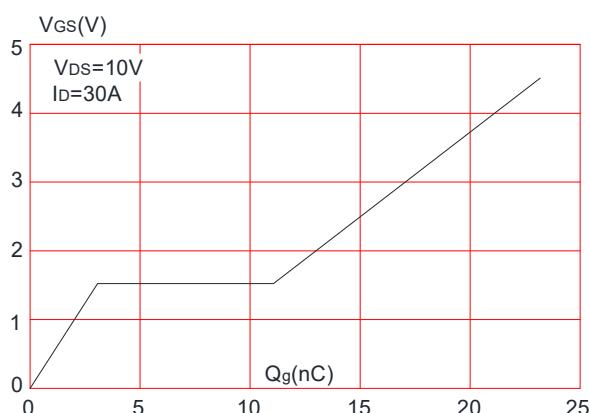


Figure 2: Typical Transfer Characteristics

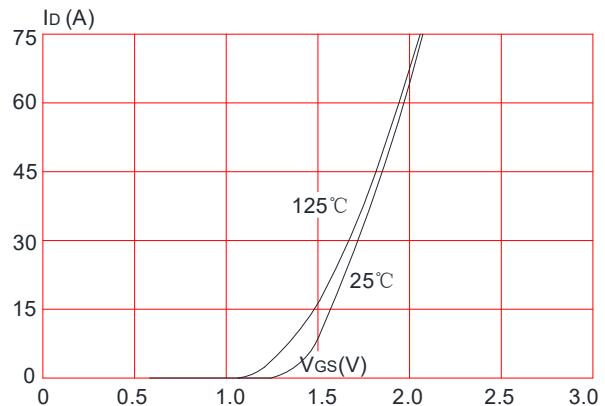


Figure 4: Body Diode Characteristics

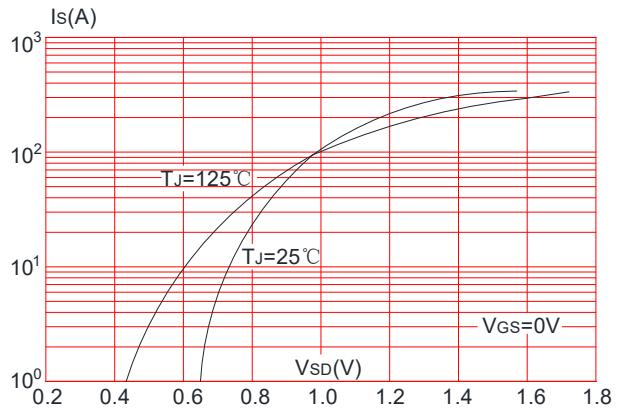


Figure 6: Capacitance Characteristics

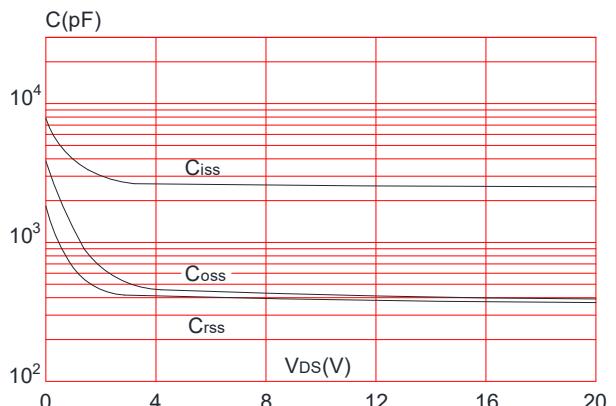


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

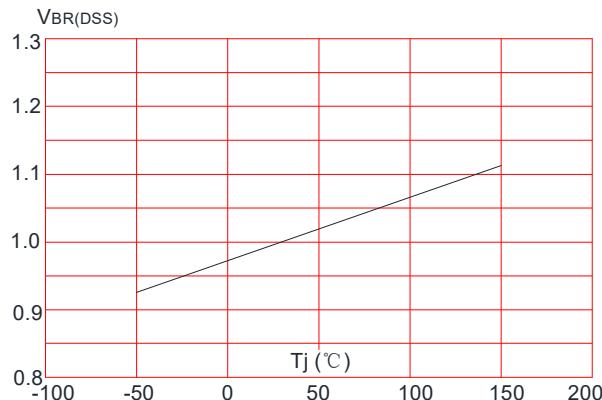


Figure 9: Maximum Safe Operating Area

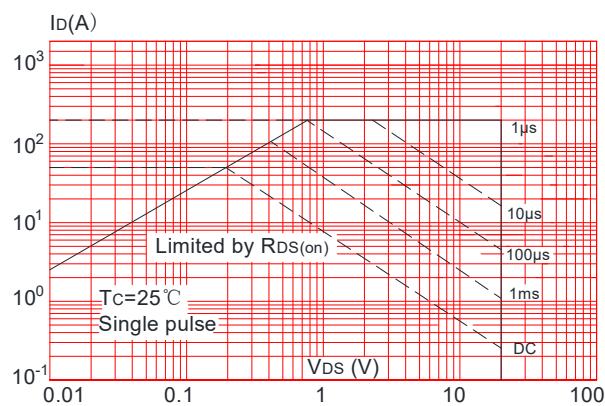


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Case

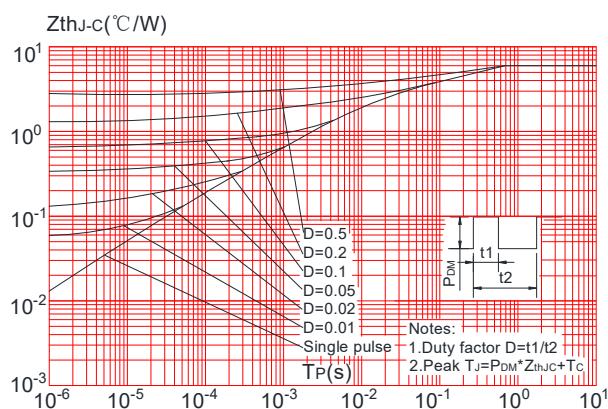


Figure 8: Normalized on Resistance vs. Junction Temperature

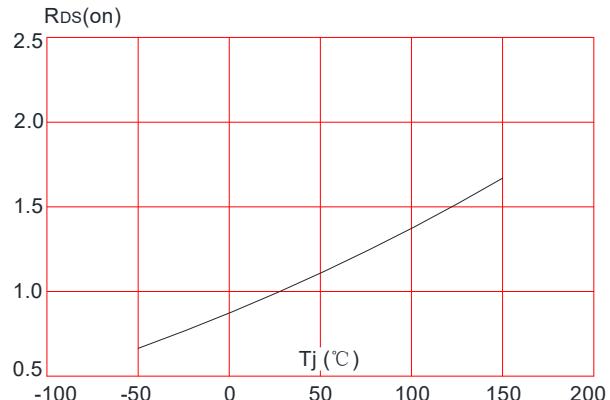
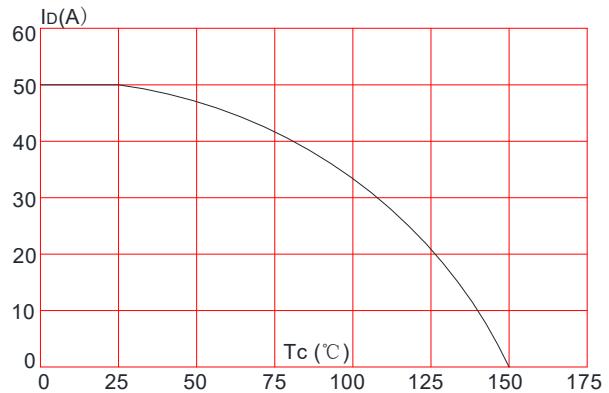


Figure 10: Maximum Continuous Drain Current vs. Case Temperature



Test Circuit

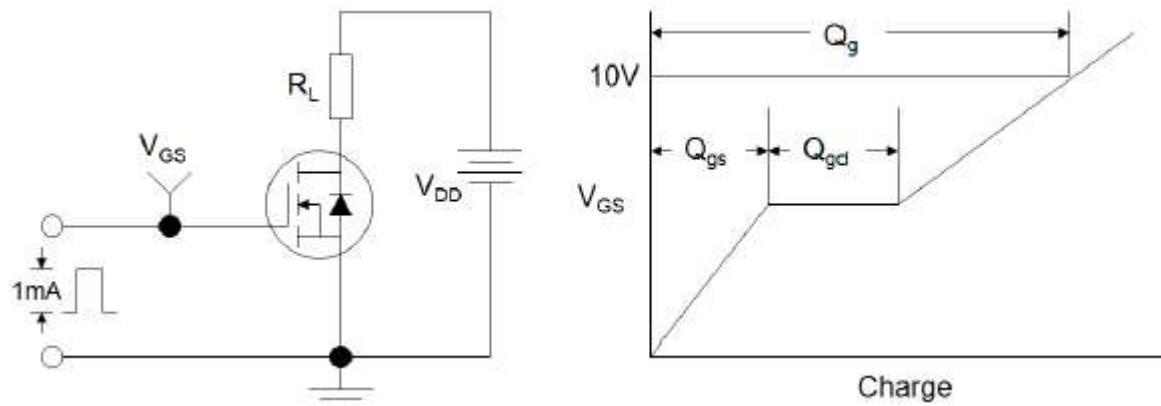


Figure 1: Gate Charge Test Circuit & Waveform

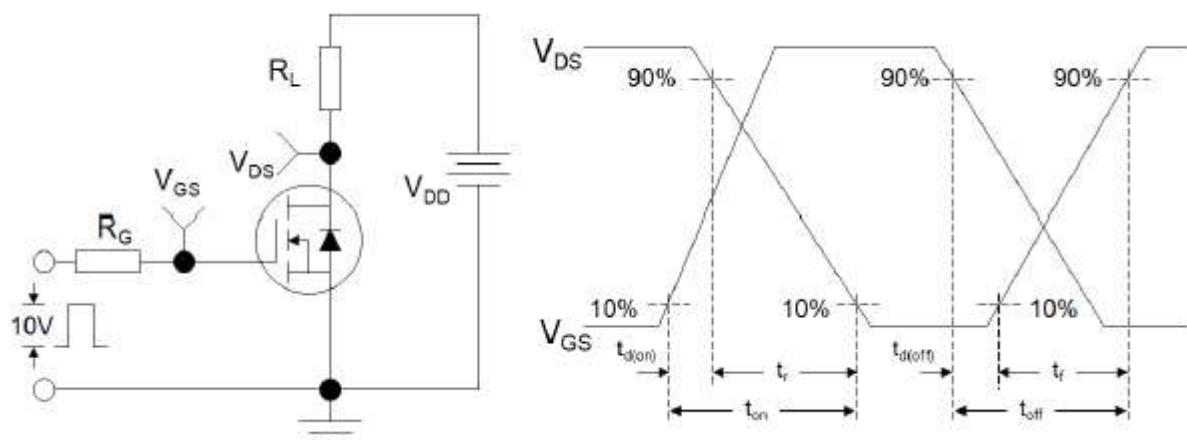


Figure 2: Resistive Switching Test Circuit & Waveforms

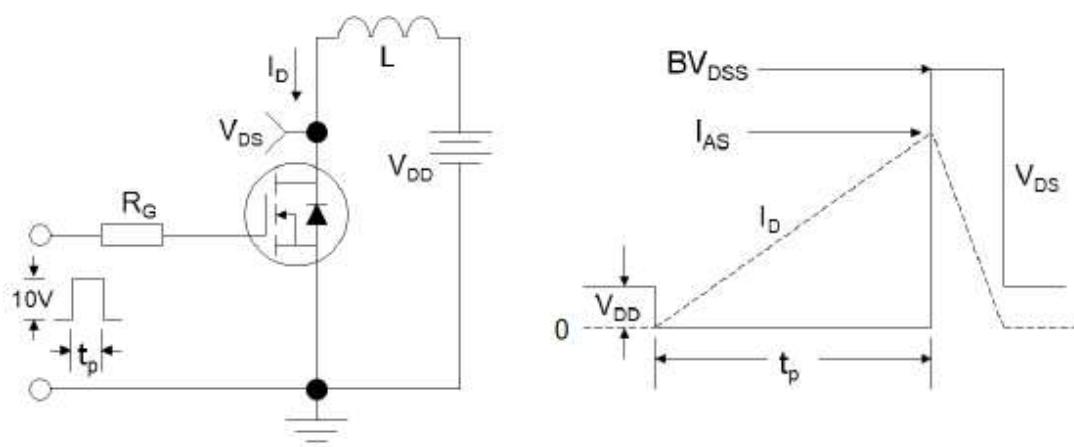
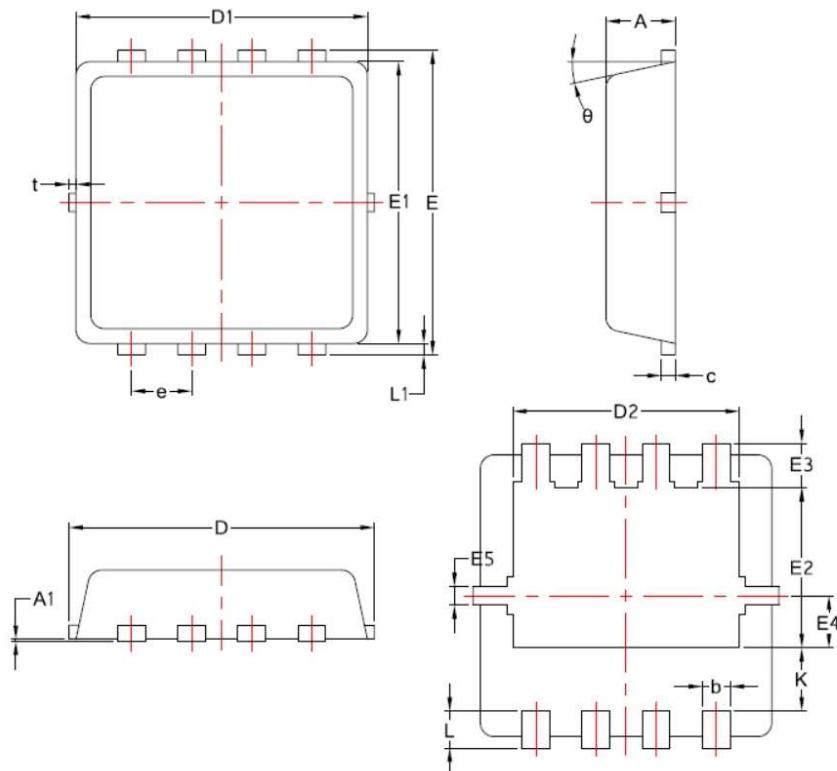


Figure 3: Unclamped Inductive Switching Test Circuit & Waveforms

Package Mechanical Data- PDFN3.3X3.3-8L



SYMBOL	COMMON		
	MM		
	MIN	NOM	MAX
A	0.70	0.75	0.85
A1	/	/	0.05
b	0.20	0.30	0.40
c	0.10	0.152	0.25
D	3.15	3.30	3.45
D1	3.00	3.15	3.25
D2	2.29	2.45	2.65
E	3.15	3.30	3.45
E1	2.90	3.05	3.20
E2	1.54	1.74	1.94
E3	0.28	0.48	0.65
E4	0.37	0.57	0.77
E5	0.10	0.20	0.30
e	0.60	0.65	0.70
K	0.59	0.69	0.89
L	0.30	0.40	0.50
L1	0.06	0.125	0.20
t	0	0.075	0.13
θ	10°	12°	14°

Information furnished in this document is believed to be accurate and reliable. However, Jiangsu JieJie Microelectronics Co.,Ltd assumes no responsibility for the consequences of use without consideration for such information nor use beyond it.

Information mentioned in this document is subject to change without notice, apart from that when an agreement is signed, Jiangsu JieJie complies with the agreement.

Products and information provided in this document have no infringement of patents. Jiangsu JieJie assumes no responsibility for any infringement of other rights of third parties which may result from the use of such products and information.

 is a registered trademark of Jiangsu JieJie Microelectronics Co.,Ltd.
Copyright ©2020 Jiangsu JieJie Microelectronics Co.,Ltd. Printed All rights reserved.